

PRELIMINARY

CY7C1019

Features

- High speed
 - —t_{AA} = 10 ns
- CMOS for optimum speed/power
- Center power/ground pinout
- Automatic power-down when deselected
- Easy memory expansion with \overline{CE} and \overline{OE} options

Functional Description

The CY7C1019 is a high-performance CMOS static RAM organized as 131,072 words by 8 bits. Easy memory expansion is provided by an active LOW chip enable ($\overline{\text{CE}}$), an active LOW output enable ($\overline{\text{OE}}$), and three-state drivers. This device has an automatic power-down feature that significantly reduces power consumption when deselected.

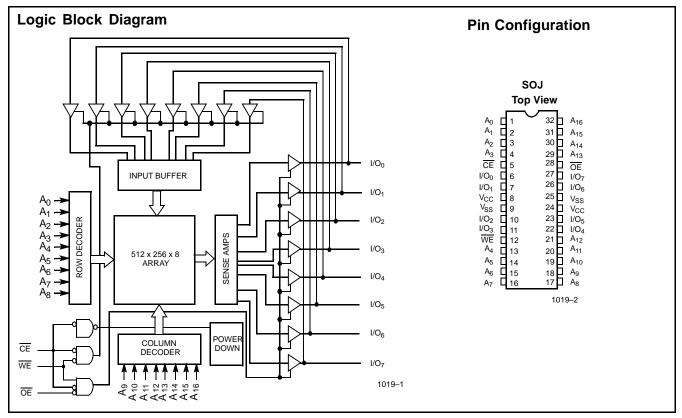
128K x 8 Static RAM

<u>Writing</u> to the device is accomplished by taking chip enable $\overline{(CE)}$ and write enable $\overline{(WE)}$ inputs LOW. Data on the eight I/O pins (I/O₀ through I/O₇) is then written into the location specified on the address pins (A₀ through A₁₆).

Reading from the device is accomplished by taking chip enable (\overline{CE}) and output enable (\overline{OE}) LOW while forcing write enable (\overline{WE}) HIGH. Under these conditions, the contents of the memory location specified by the address pins will appear on the I/O pins.

The eight input/output pins (I/O₀ through I/O₇) are placed in <u>a</u> high-impedance state when the <u>device</u> is deselected (CE HIGH), the <u>outputs</u> are disabled (OE HIGH), or during a write operation (CE LOW, and WE LOW).

The CY7C1019 is available in standard 400-mil-wide SOJs.



Selection Guide

		7C1019–10	7C1019–12	7C1019–15
Maximum Access Time (ns)		10	12	15
Maximum Operating Current (mA)		240	220	200
	L	210	190	175
Maximum Standby Current (mA)		10	10	10
	L	1	1	1

Shaded areas contain advance information.

Cypress Semiconductor Corporation Document #: 38-05055 Rev. **

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Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage on V _{CC} to Relative $GND^{[1]}$ –0.5V to +7.0V
DC Voltage Applied to Outputs in High Z State $^{[1]}$ 0.5V to V_{CC} + 0.5V
DC Input Voltage ^[1] 0.5V to V_{CC} + 0.5V

Electrical Characteristics Over the Operating Range

Current into Outputs (LOW)	20 n	nA
Static Discharge Voltage (per MIL-STD-883, Method 3015)	>200 ⁻	1V
	000	•

Latch-Up Current......>200 mA

Operating Range

Range	Ambient Temperature ^[2]	v _{cc}
Commercial	0°C to +70°C	$5V \pm 10\%$

				7C10	019-10	7C10	019-12	7C10	019-15	
Parameter	Description	Test Conditions		Min.	Max.	Min.	Max.	Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	V_{CC} = Min., I_{OH} = -4.0 m	2.4		2.4		2.4		V	
V _{OL}	Output LOW Voltage	V _{CC} = Min., I _{OL} = 8.0 mA			0.4		0.4		0.4	V
V _{IH}	Input HIGH Voltage			2.2	V _{CC} + 0.3	2.2	V _{CC} + 0.3	2.2	V _{CC} + 0.3	V
V _{IL}	Input LOW Voltage ^[1]			-0.3	0.8	-0.3	0.8	-0.3	0.8	V
I _{IX}	Input Load Current	$GND \leq V_I \leq V_{CC}$		-1	+1	-1	+1	-1	+1	μΑ
I _{OZ}	Output Leakage Current	$GND \leq V_I \leq V_{CC},$ Output Disabled		-5	+5	-5	+5	-5	+5	μΑ
I _{CC}	V _{CC} Operating	V _{CC} = Max.			240		220		200	mA
	Supply Current	$I_{OUT} = 0 \text{ mÅ},$ f = f _{MAX} = 1/t _{RC}	L		210		190		175	
I _{SB1}	Automatic CE	Max. V_{CC} , $\overline{CE} \ge V_{IH}$			40		40		40	mA
	Power-Down Current —TTL Inputs	$V_{IN} \ge V_{IH}$ or $V_{IN} \le V_{IL}$, f = f _{MAX}	L		20		20		20	
I _{SB2}	Automatic CE Max. V _{CC} ,				10		10		10	mA
	Power-Down Current —CMOS Inputs	$\begin{array}{l} CE \geq V_{CC} - 0.3V, \\ V_{IN} \geq V_{CC} - 0.3V, \\ or \; V_{IN} \leq 0.3V, \; f=0 \end{array}$	L		1		1		1	

Shaded areas contain advance information.

Capacitance^[3]

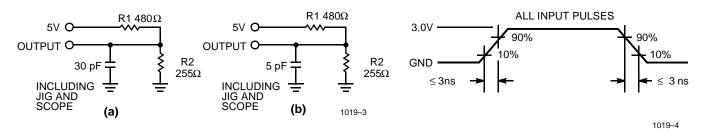
Parameter	Description	Test Conditions	Max.	Unit
C _{IN}	Input Capacitance	$T_{A} = 25^{\circ}C, f = 1 \text{ MHz},$	6	pF
C _{OUT}	Output Capacitance	$V_{CC} = 5.0V$	8	pF

Notes:

V_{IL} (min.) = -2.0V for pulse durations of less than 20 ns.
 T_A is the "instant on" case temperature.
 Tested initially and after any design or process changes that may affect these parameters.



AC Test Loads and Waveforms



Equivalent to: THÉVENIN EQUIVALENT 167Ω -0 1.73V OUTPUT O

Switching Characteristics^[4] Over the Operating Range

		7C10	19-10	7C1019-12		7C1019-15		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Unit
READ CYC	LE							
t _{RC}	Read Cycle Time	10		12		15		ns
t _{AA}	Address to Data Valid		10		12		15	ns
t _{OHA}	Data Hold from Address Change	3		3		3		ns
t _{ACE}	CE LOW to Data Valid		10		12		15	ns
t _{DOE}	OE LOW to Data Valid		5		6		7	ns
t _{LZOE}	OE LOW to Low Z	0		0		0		ns
t _{HZOE}	OE HIGH to High Z ^[5, 6]		5		6		7	ns
t _{LZCE}	CE LOW to Low Z ^[6]	3		3		3		ns
t _{HZCE}	CE HIGH to High Z ^[5, 6]		5		6		7	ns
t _{PU}	CE LOW to Power-Up	0		0		0		ns
t _{PD}	CE HIGH to Power-Down		10		12		15	ns
WRITE CYC	CLE ^[7,8]			•				
t _{WC}	Write Cycle Time	10		12		15		ns
t _{SCE}	CE LOW to Write End	8		9		10		ns
t _{AW}	Address Set-Up to Write End	7		8		10		ns
t _{HA}	Address Hold from Write End	0		0		0		ns
t _{SA}	Address Set-Up to Write Start	0		0		0		ns
t _{PWE}	WE Pulse Width	7		8		10		ns
t _{SD}	Data Set-Up to Write End	5		6		8		ns
t _{HD}	Data Hold from Write End	0		0		0		ns
t _{LZWE}	WE HIGH to Low Z ^[6]	3		3		3		ns
t _{HZWE}	WE LOW to High Z ^[5, 6]		5		6		7	ns

Shaded areas contain advance information.

Note:

Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and 30-pF load capacitance. 4.

t_{HZOE}, t_{HZCE}, and t_{HZWE} are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage. 5.

6.

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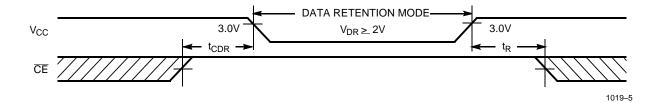
8.



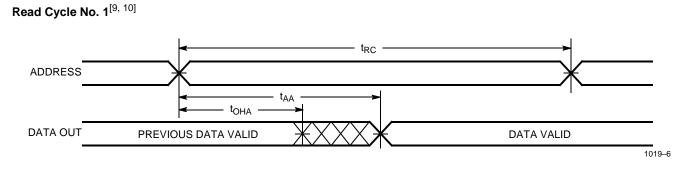
Data Retention Characteristics Over the Operating Range (L Version Only)

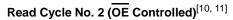
Parameter	Description	Conditions	Min.	Max	Unit
V _{DR}	V _{CC} for Data Retention	No input may exceed V _{CC} + 0.5V	2.0		V
I _{CCDR}	Data Retention Current	$\frac{V_{CC}}{CE_1} = V_{DR} = 3.0V,$ $CE_1 \ge V_{CC} - 0.3V,$		300	μA
t _{CDR} ^[3]	Chip Deselect to Data Retention Time	$V_{\rm IN} \ge V_{\rm CC} - 0.3V$ or $V_{\rm IN} \le 0.3V$	0		ns
t _R	Operation Recovery Time		t _{RC}		ns

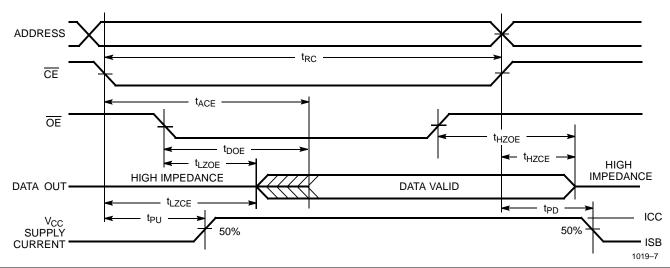
Data Retention Waveform



Switching Waveforms







Notes:

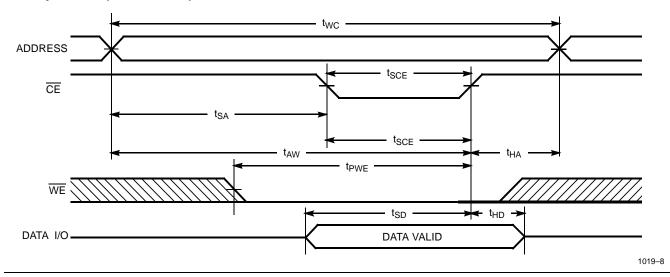
9. <u>Device is continuously selected</u>. \overline{OE} , $\overline{CE} = V_{||L}$.

WE is HIGH for read cycle.
 Address valid prior to or coincident with CE transition LOW.

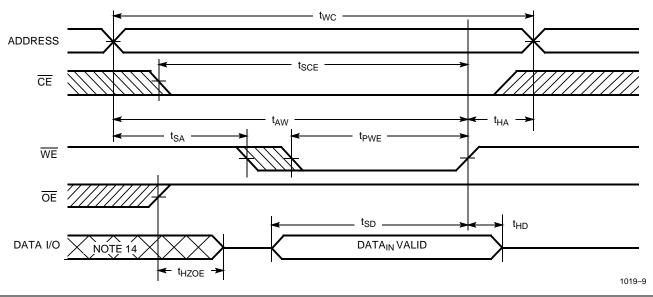


Switching Waveforms (continued)

Write Cycle No. 1 (CE Controlled)^[12, 13]



Write Cycle No. 2 (WE Controlled, OE HIGH During Write)^[12, 13]



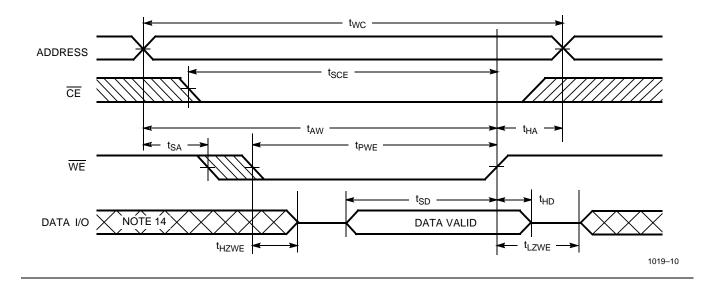
Notes:

- 12. Data I/O is high impedance if OE = V_{IH}.
 13. If CE goes HIGH simultaneously with WE going HIGH, the output remains in a high-impedance state.
 14. During this period the I/Os are in the output state and input signals should not be applied.



Switching Waveforms (continued)

Write Cycle No. 3 ($\overline{\text{WE}}$ Controlled, $\overline{\text{OE}}$ LOW)^[13]



Truth Table

CE	OE	WE	I/O ₀ –I/O ₇	Mode	Power
Н	Х	Х	High Z	Power-Down	Standby (I _{SB})
Х	Х	Х	High Z	Power-Down	Standby (I _{SB})
L	L	Н	Data Out	Read	Active (I _{CC})
L	Х	L	Data In	Write	Active (I _{CC})
L	Н	Н	High Z	Selected, Outputs Disabled	Active (I _{CC})

Ordering Information

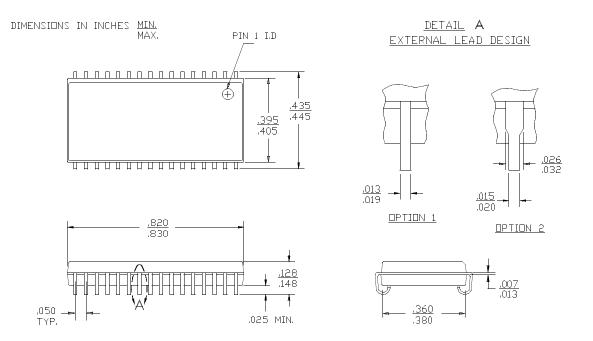
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
10	CY7C1019-10VC	V33	32-Lead 400-Mil Molded SOJ	Commercial
	CY7C1019L-10VC	V33	32-Lead 400-Mil Molded SOJ	
12	CY7C1019-12VC	V33	32-Lead 400-Mil Molded SOJ	Commercial
	CY7C1019L-12VC	V33	32-Lead 400-Mil Molded SOJ	
15	CY7C1019-15VC	V33	32-Lead 400-Mil Molded SOJ	Commercial
	CY7C1019L-15VC	V33	32-Lead 400-Mil Molded SOJ	

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Package Diagram

32-Lead (400-Mil) Molded SOJ V33



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**	107246	09/10/01	SZV	Change from Spec number: 38-00440 to 38-05055	